

# TFBGA\_ASC88x

Pb and Halogen free; 484 balls

8 February 2016

Package information

## 1. Package summary

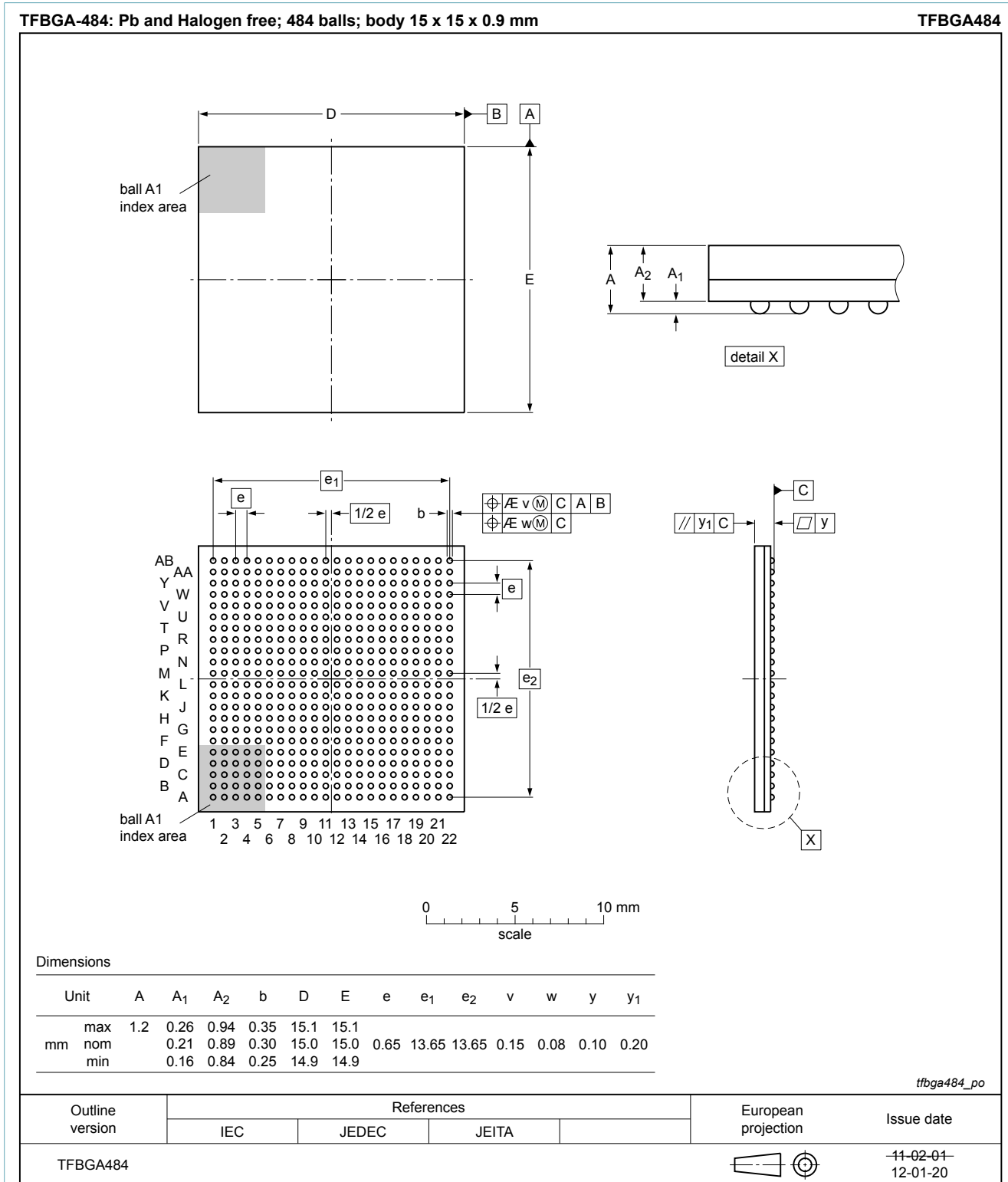
Terminal position code	B (bottom)
Package type descriptive code	TFBGA_ASC88x
Package type industry code	TFBGA484
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	9-3-2012

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		14.9	-	15	15.1	mm
E	package width		14.9	-	15	15.1	mm
A	seated height		-	-	-	1.2	mm
A <sub>2</sub>	package height		0.84	-	0.89	0.94	mm
e	nominal pitch		-	-	0.65	-	mm
n <sub>2</sub>	actual quantity of termination		-	-	484	-	



## 2. Package outline



**Fig. 1. Package outline TFBGA484 (TFBGA\_ASC88x)**

### 3. Legal information

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